

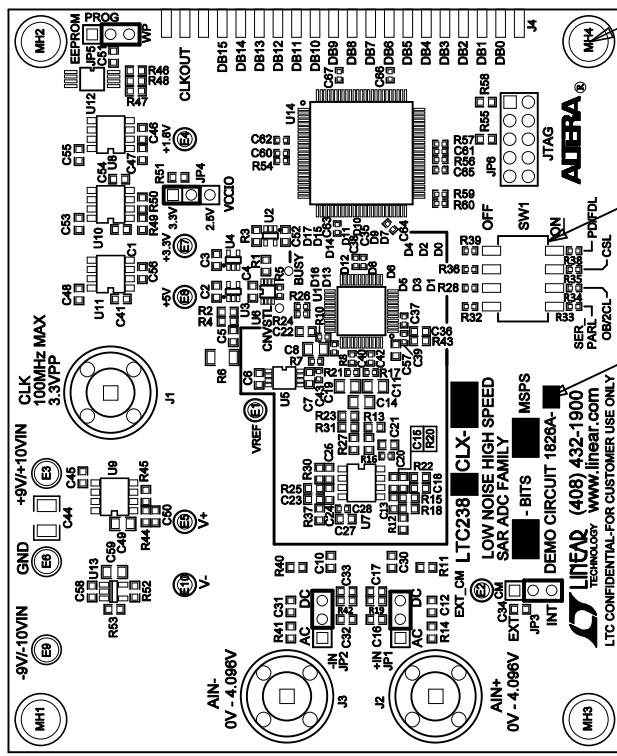
## REVISION HISTORY

ECO REV	DESCRIPTION	APP. ENG.	DATE
1	1ST PROTOTYPE	GUY H.	05/16/11
2	2ND PROTOTYPE	GUY H.	06/28/11
3	PRODUCTION	GUY H.	01/12/12

## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240°C.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
6. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:

7. [Diagram showing four standoffs labeled MH1-MH4, each with a height of 4X STANOFF, NYLON, SNAP ON.]



8. MARK EACH LTC PART NUMBER AND ASSEMBLY TYPE WITH BLACK PERMANENT MARKER AS SHOWN IN TABLE BELOW:

ASSY	U1	Bits	Mps	R60
DC1826A-A	LTC2387CLX-18	18	2.5	301
DC1826A-B	LTC2388CLX-18	18	1	301
DC1826A-C	LTC2387CLX-18	18	0.5	301
DC1826A-D	LTC2388CLX-18	18	0.25	301
DC1826A-E	LTC2389CLX-18	16	2.5	—
DC1826A-F	LTC2388CLX-18	16	1	—
DC1826A-G	LTC2387CLX-18	16	0.5	—
DC1826A-H	LTC2386CLX-18	16	0.25	—



APPROVALS		LINEAR TECHNOLOGY	
PCB DES.	RB	APP ENG.	GUY H.

TITLE: TOP ASSEMBLY DRAWING  
LOW NOISE HIGH SPEED SAR ADC FAMILY

SIZE	IC NO.	REV.
N/A	1826A Rev3.PCB	3

SCALE = NONE FILENAME: 1826A Rev3.PCB SHT 1 OF 2

9. SW1 DEFAULT SETUP:  
SET LOW FOR: SER\_PARL;OB2CL;CSL;PDFDL.